



OCP
APAC
SUMMIT

TAIPEI CITY



2027 OCP APAC SUMMIT

SPONSOR PROSPECTUS

10–12 August, 2027 | TaiNEX 2 | Taipei City, Taiwan



About the OCP APAC Summit



The OCP APAC Summit is the region's flagship gathering for open data center innovation. Hosted annually in Taipei City, the Summit convenes global hyperscalers, hardware vendors, telecoms, colocation providers, and solution providers to accelerate adoption of OCP-recognized designs. The 2026 edition drew strong attendance and engagement, underscoring the growing importance of APAC within the global OCP Community — and has already generated enthusiasm among organizations preparing to sponsor and participate in 2027.

2026 Program Themes

- AI Clusters
- AI Computing Continuum
- Chiplets & Advanced Packaging
- Cooling Environments
- Future Technologies Symposium
- Market Impact & Adoption
- Networking
- Open Data Center for AI: Rack & Power, Power Distribution and Facility Design
- Photonics
- Server
- Storage & Memory



Keynotes kicked off the event with amazing speakers from AMD, Applied Materials, Arm, ASE, Broadcom, Google, Microsoft, NTT, NVIDIA, and TSMC.

Regional Importance

The APAC region is one of the fastest-growing markets for hyperscale and enterprise data centers. Leading companies including AMD, Applied Materials, Arm, ASE, Broadcom, Google, Microsoft, NTT, NVIDIA, and TSMC have actively contributed to OCP initiatives across the region. Co-hosted in 2026 by the AI-on-Chip Taiwan Alliance (AITA), the Cloud Computing and IoT Association in Taiwan (CIAT), and the IOWN Global Forum, the APAC Summit demonstrates OCP's strong partnership with regional ecosystems to drive global adoption of open infrastructure.

Community Impact

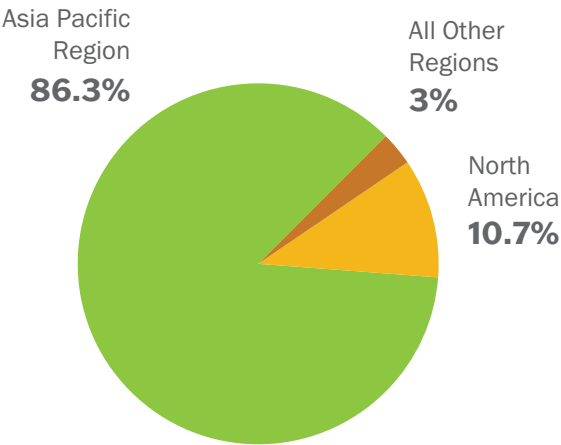
- The 2026 Summit drew nearly 2,500 attendees in Taipei City.
- More than 1,700 Asia-based workshop participants underscored strong interest in AI and data center design
- APAC accounted for 36% of OCP-recognized equipment shipments in 2026 — a key growth driver for the global community.

OCP APAC 2026 by the Numbers

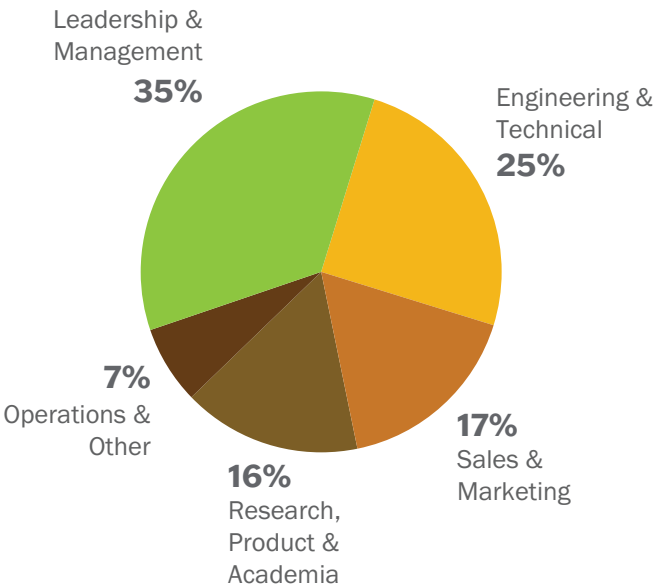


The OCP APAC Summit reflects the strength of a global community committed to openness, efficiency, and collaboration. These numbers illustrate the diversity of participants, the breadth of content, and the growing influence of APAC in the adoption of OCP solutions.

Attendees by Region

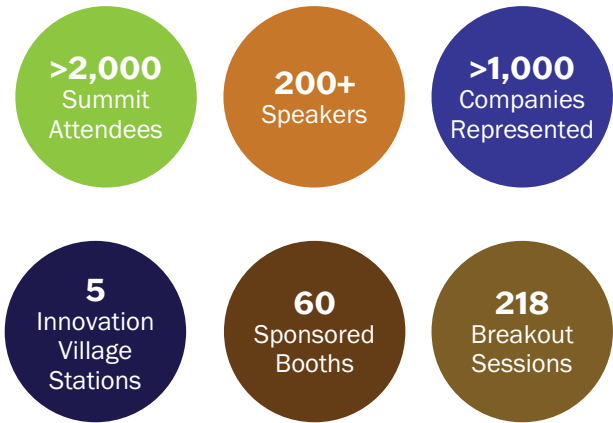
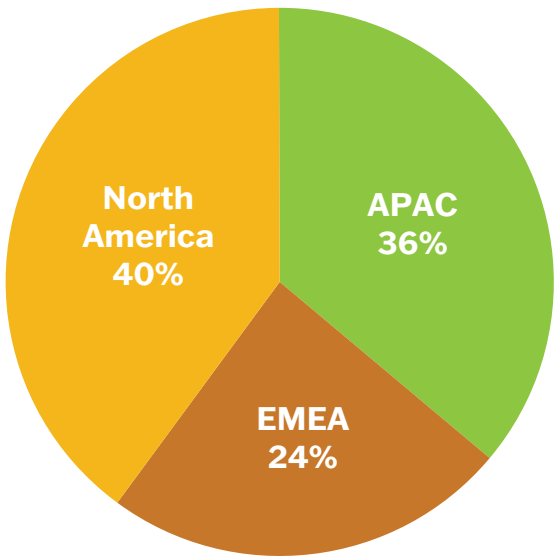


Attendees by Job Function



OCP Recognized Equipment Shipments (2026 Global Share)

2026 Summit Stats



Data based on 2026 OCP APAC Summit highlights; final 2027 attendee demographics will be published after the event.

OCP APAC 2026 Sponsors



The following organizations supported the 2026 OCP APAC Summit through sponsorships and partnerships, reflecting the collaborative spirit of the OCP community.

Previous Sponsors

9elements	Danfoss Power Solutions	Sil-More Industrial
ABB	DigiTimes	SONic Foundation
Acbel Polytech	Edgecore Networks	STULZ
actnano	Empower Semi	Submer
AMD	Google	Sumitomo Electric Lightwave
AMI	Gredmann Group	Supernano
Amplink	HARTING	SuperX Digital Power
Anritsu	Insyde Software	SwitchLab
Arm	Intel	SystemReady by Arm
ASE, Inc.	Introspect Technology	TechNews
ASPEED Technology	Kaori Heat Treatment	TE Connectivity
ASRock Rack	Keysight Technologies	Transpak
Astron Connectivity	Kipo Technology	UfiSpace
Axiado Corporation	Legrand	Veginean Technology
BellWether	LOTES	Viavi Solutions
BizLink	MaxLinear	vinatech
Broadcom	Microelectronics Magazine	Voltronic Power
CEJN	Microsoft	XCENA
Celestica	MiTAC Computing	Xerendipity
Chroma ATE	Murata	XING Mobility
CIAT	Nuvoton	Xmight Smart Energy
CoolIT Systems	nVent	Y.S. Technology
Corning	Pegatron	
CPC - Colder Products	Samtec	



2026 Organizations Represented

3M	Artilux	Chant Sincere Co.,Ltd	E
9elements	Artron Tech Inc.	Chenbro	Eagletek
A	Asahi Kasei Microdevices	Cheng Ci Corporation	Eaton
A-sink Green Material Corporation	Ascend Materials	Chenlux Technology Ltd.	Ebmpapspt
A&A Technology Corporation	Ascentech K.K.	Chi Chen Technology Co.,Ltd.	Echion Technologies
ABB	ASE Group	Chicony Electronics Co., Ltd	Ecolab
Aboda	Asetek	CHIHONG TECHNOLOGY	Economic Daily News
AcBel Polytech Inc.	Asia Vital Components	Chongqing Baiyushun Precision Industry	Edgecore Networks
Accela Sales Management Corp (ASMC)	Asink Green Material Corporation	Chosun University	Eetimes
Accton	ASPEED Technology	Chroma ATE Inc.	EISG
Aces Electronics	Aspencore	CHSE	Elite Materials Co., Ltd.
Acon Optics	ASRock Rack Inc.	CHT	eMemory Technology Inc.
Actapio, Inc.	Astemo Cypremos	Chunghwa Telecom Co.	Empower Semiconductor
Actnano	Astera Labs	Cisco Systems Inc.	Energy Security Agency
Acuitas Research	Astron Connectivity	Citadel Asia	Energy Storage Device Business Division
Adi	ASUSTeK	Citigroup	Enermax
Ador Powertron Limited	Asymmetry Partners	Clariant Chemicals Technology	Envalior Engineering Materials
Adtek	ATMD (Hong Kong) Ltd.	Cloudalpha Capital	Epic Microsystems
Advanced Energy	ATMOCE	Clsa Sinopac	Eridu
Advanced Fiber Resources	Atmosphere	CNT Singapore	Eugene
Advanced RD	ATP Electronics	Coherent	Everpure
Advantest	AUO Corporation	Commonwealth Magazine	Everwell Global
Aes Holding Co	Aurorium LLC	Compal Electronics, Inc	Evonik
AGC	Avient Corporation	Compeq	Expert International Mercantile Corp.
AHSI	Avrix Systems Inc.	Component Quality And Technical	F
AIC Inc.	Axiado	Compute K. K.	Fabrinet
Aig	Ayar Labs	ConnectingPoints	Fast SiC Semiconductor Inc.
AimToG	B	ConnPro Industries Inc.	Fastech Advanced Assembly Inc
Aivres	Baltimore Aircoil Company	Contitech	FDK
Ajou University	Bank Of America	Cooler Master	Feilong Auto Components Co.
Aletheia Capital	BASF	Corintis	Fhtrust
Alfa Laval	BBIX Inc.	Corning	Ficer
Algood	Bbsakura Networks Inc.	CPC	First Capital Management
Allegro	Beijing Green Hill Innovation	Crater Networks, Inc.	First Security
Allianz Global Investor	Belfuse	Credo	Flex
Allion Labs	Belimo	Critical Risk Solution	FMAD Engineering
Alltek	Bellwether Electronic Corp.	CSA Group Test and Certification	Fortune Education Consulting Co
Alpha Lumio	Bender Gmbh & Co. Kg	CTBC Investments	FOUR-P PART CO.,LTD.
Alpha Six Capital	BenQ Materials	CTC (Itochu)	Foxconn
Alqais	Besi Singapore Pte.	Ctci Foundation	Foxtron Vehicle Technologies
Altera	Beyondsoft Consulting	Cybertech Electronics Co.	Fsas Technologies
Amazon	Bfw Solutions	Cyient Semiconductor	Fubon Asset Management
Amazon Web Services	Bizlink Technology, Inc.	Cyntec	Fubon Securities Investment Consulting\
Amber Semi.	Bourns India Pvt Ltd	Cypress Battery	Fuh Hwa Trust
AMD	Brillink Inc.	D	Fujifilm Sonosite
American Power Conversion Holding	BRINKMANN PUMPS, GTC Company	D-REX Corporation	Fujitsu
Americase	Broadcom	DAEDAELUS	Funda Ai
AMI	Browave Corporation	Daikin Industries Inc.	Furukawa Electric Co.
Amis Capital Management	Business Today	Daiwa Capital Markets	G
Ampere Computing	Business Weekly	Danfoss	Gaam
Amphenol	C	Dawnhoof Electrical	Gdplus Enterprises
AmpLink	C-Tech United Corp.	Daxin Capital Management	Gemtek Technology
Ams Osram	Cadence Design Systems	Dayone Data Centers	Georg Fischer
Analog Devices	Calnex Solutions	DC3	Georgia Institute of Technology
Analog Power	Capital Investment Management Corp.	Dcenc	GIC
Anritsu	Capxon Electronic Technology Co.	DCLC	Gigacomputing Technology
Apapolo Technology Co., Ltd.	Capxon Technology Limited	Defog	GIS Holding
Applied Materials	Cathaysite	Dell Technologies	Global Electronic Association (GEA)
APRESIA Systems	CBMM	Delta Electronics	Global Monthly Views Magazine
APTD	CCB International	Dexerials Corporation	Global Standard Technology
Ara Cooling Solutions	CCI Corporation	Diamond Foundry	Global Switch
Aria Networks	CCT	DiCon Fiberoptics, Inc.	Global Unichip
Arista Networks	CDC Pneumatics Corp	Digitimes	GlobalFoundries
Arkema	ceEntek Pte Ltd	Donaldson	GMT GLOBAL Inc.
Arm	CEJN	DS Energeia Technology Ltd.	Goldman Sachs
Arohi Asset Management	Celestica	Dymon Asia	Good Will Instrument
Arrow Electronics	Ceres Power	Dynapack	Google

2026 Organizations Represented

Goreal Electric
Grand Leader Management Constant Co.
Graphcore
GREATWALL POWER SUPPLY TECHNOLOGY
Gredmann Group
Grenzbach Data Center Solutions
Grundfos
GST(Global Standard Technology)
GUC
Gus Technology CO.

H

Hanwha
Harting
Harvatek
HazMat Safety Consulting, LLC
HCL Technologies
Hedgehog
Hefei Shinhoo Canned Motor Pump
Henkel
Heron Power
Hetone Enterprise
Hicon Co., Ltd., Taiwan Rep. Office
Hitachi Ltd.
Home Media Group
Hon Hai Precision Industry
Hon Hai Technology Group
Howteh
HPE
HSBC
Huawei
Hwaseung Corporation
Hyper

I

IDC
IIP, R&D
Immix Energy
Incavo
Indium Corporation
Industrial Technology Research Institute
Infineon Technologies
Ingrasys
innolux
Institute For Information Industry
Institute of Technical Education Singapore
Insyde Software
Intel
Internet Initiative Japan Inc.
Introspect Technology
Inventec

IOActive
IOWN GF
iPRONICS
IQ Silicon
Isaiah Research
Itest Technology Co., Ltd.
ITOCHU Techno-Solutions Corporation

J

J.P.Morgan
J&J Investment
Jabil
Jgc Corporation
JMicron
Johnson Electric
JPC Connectivity
Jws Technology
JX Advanced Metals Corporation

K

Kanto Yakin Kogyo Co., Ltd.
Kaori Heat Treatment
KDDI
Keysight
KGI Investment Advisory
Kingsun Investment
KIOXIA Corporation
Kipo
Kirti Telnet Pvt.Ltd
Korea Institute Of Machinery & Materials
Korea Packaging Integration Association
Kraut.hosting GmbH
KUHLTHERM PRIVATE LIMITED
Kyocera Corporation

L

Largan Precision
Lattice Semiconductor
Leadertech
Lego Asset Management
Legrand
Lenovo
Leoni
Lightcounting
Lightmatter
Linque
Lintes Technology Co., Ltd.
Liquidpulse
LiquidStack Limited
Lisconn
LITEON Technology
Littelfuse Inc.

Live Optonics
Lotes
LS Cable & System
Luxcasting International Group
Luxor Technology Corporation
Luxshare Tech

M

Macnica
Macquarie
Macroblock, Inc
Macronix
Marvell
Maxlinear
MC Digital Realty Inc.
Mediatek
MENNEKES Industrial Electric
Merck Performance Materials Ltd.
Mercuries Life Insurance
MESH-X
Meta
Micro-electronics Magazine
Microchip
Microsoft
Millennium Capital Management
Minebea Technologies
MIRRORDAILY
MiTAC Computing
Mitsubishi Electric
Mixed-signal Devices, Inc
MLP Hong Kong
MO - Motion
Molex
Molice
Momentum International Corp
MoneyDJ
Moog Controls Hong Kong Ltd.
Morgan Stanley
Motion
Moxa
MUFG Bank
Multek
Murata Manufacturing
Musashi Energy Solutions

N

Nalco Water
National Taiwan University
National University of Singapore
Navitas
Nexavant

Next Opto-tech Inc.
Nextapplenews
Nexthop Systems Inc.
NextSilicon
Nomura Securities
Novamat Applied Material
Novatek
Novolinc
NTT
NTT DATA
NTT Facilities
NTT Innovative Devices
Nuvoton Technology
nVent
NVIDIA
NXP Semiconductors
NYCU

O

Oetiker
Omdia
Omniva
Onion Software
Optical fiber and connectivity
Optimus Prime
Opixon Technology Inc
Osaka University

P

PALC Networks
Palo Alto Electron
PAN-ASIA CHEMICAL CO.
Panasonic
Pantek Technology Corp.
PANTHEON.tech
Parade
Parker Hannifin
Patech Fine Chemicals
Pegatron Corporation
Petronas
Phison Electronics
Phoenix Contact
Phoenixes Capital
Pie
Pleiad Investment Advisors
Point2 Technology
Point72
Points Of Presence Pte. Ltd.
Power Integrations GmbH
Preferred Networks
Progranalog



2026 Organizations Represented

PTTOR
PUFSecurity
Pyxis lab

Q

Qinivicta
Qnity Electronics
Qualcomm
Quanta
Quarktek Capital
Quintessent

R

R&M Electronics
Radiall Electronics
Rakuten Mobile
Ralliant
Rambus
Rapidus
Raritan
Realtek
Rectifier Technologies
Red Hat
Reedsemi
Reinhausen Asia Pacific
Renesas Electronics
Renhausen Taiwan Ltd.
Resolute Photonics
Reuters
Richards Industrial
Richtek Technology
Rittal
Rotork

S

Samjintech Co.
Samsung
Samtec
Sanyo Denki Taiwan
SBI E2-Capital Securities Limited
Schie
SCHNEIDER ELECTRIC
Schonfeld
Schröders
Sciencetech corporation
Seagate
SemiAnalysis
SemiExponent
Semivision
SENKO Advanced Components
Sensata Technologies
Setra System
Shenzhen iTest Technology Co.
Shin Kong Life Insurance
Shin-etsu Thermal Interface Materials Dist.
Shinwa Controls America
SIKA Dr. Siebert & Kühn GmbH & Co.KG

Sil-More Industrial
Silicon Motion
SiLith
SIMS LIFECYCLE SERVICES
Singatron Enterprise Co.
SINICA Academia
Sk Enmove
SK Innovation
Skyworks
Solar Applied Material Technologies
Solatice Advanced Materials
Solidigm
SOLSTICE
Sonhong Trade
SPAL
SPEC (Standard Performance Evaluation Corp.)
Spil
Stanford University
StarFive Technology
Stäubli Electrical Connectors Ag
Stealth
STMicroelectronics
Strait Capital
Studio Bookmark
Stulz Asia Hub
Submer
Sumitomo Electric
Sumitomo Precision Products
Sumitomo Riko Company Limited
Sungrow power
Sunon
Super Hoze Industries Pvt Ltd
Superliq
Supermag company
Supermicro
Superx Digital Power
Suzhou Youlong Rubber & Plastic
Precision Manufacturing
Swagelok Taiwan
SwarmOne
Switchlab Inc.
Synic
Synopsis

T

T-Global Technology Co.
Tairen Capital
Taishin Securities Investment Trust Co.
Taiwan Chemi-Con Corporation
Taiwan Institute of Economic Research (TIER)
Taiwan Life Insurance Co., Ltd
Taiwan Nitta Filter Co.,Ltd
Taiwan Semiconductor and Optronics

Materials and Devices Association
Taiwanlife
Taiwanplus
Taiyiaeh Enterprise Co.,Ltd
TAIYO YUDEN CO.,LTD
TC Technology
TE Connectivity
Techdesign House D.o.o Beograd
Techgo
Techmation Co., Ltd
Technews
TELE System Communications Pte Ltd.
Teledyne LeCroy
Telcap
Temasek Global Investments
Tenstorrent
Tera Electronics Corp.
Teradyne
Terahop
Tetrel Security
Texas Instruments
The CID Group
The Linux Foundation
The Specialty Mfg. Co.
The University of Osaka
The University of Tokyo
Thermocirca
Tokyo Ohka Kogyo
Toshiba
Transglobe
Transpak
Treeline Advisors
Trend Power Technology
Trendforce
Trendpower
Trinity Thermal Solutions
Tristone Capital
Truwater
TSIT
TSMC
TTS
TUV Rheinland
TXC Corporation

U

Ufispac
UL Solutions
UMC Capital
Underwriters Laboratories Taiwan Co.
Uneec
Uni-President Asset Management Corporation
Unimicron
United news group
Universal Global Scientific Industrial Co.

University Of Illinois At Urbana-Champaign
University Of Seoul
Upscale AI
Uravu labs
Uu Green Power

V

Valvoline Global Operations
VAST Data
Veginean Technology Co.
Vertiv
Vexa
Via Next Technologies, Inc.
VIAVI Solutions
Voltronic Power
Vso Electronics Co.

W

W Investment
Wafer Works
Walmart Technology Ltd.
Walsin Lihwa Corporation
Wealth Magazine
Well Shin Technology Co.
WI Harper
Winbond Electronics Corporation
Windarc Technology Co., Ltd.
Winstek Semiconductor Inc.
Wistron Corporation
Wiwynn
WNC Corporation
Wolfsped
WPG Holdings
Wt Microelectronics

X

Xcena
Xerendipity Global Co.
Xfusion International
Xing Mobility
Xmight Smart Energy
Xunuo Technologies
Xylem

Y

Yageo Corporation
Yen Sun Technology Corp.
Yggdrasil Capital
Yuanta Securities
Yushiro Inc.

Z

Ziehl-Abegg (Thailand) Limited
ZIITEK TECHNOLOGY
Zincfive
Zutacore
Zykel Communication

Schedule Overview

The 2027 OCP APAC Summit will bring together keynotes, breakout sessions, expo hall and networking opportunities across three days. The sample agenda highlights the program structure; final session details and speakers will be announced as the event approaches.

Day 0: Tuesday, 10 August 2027*

Time	Event
Morning	Registration
Afternoon	Colocated Workshops

Day 1: Wednesday, 11 August 2027*

Time	Event
Morning	Registration
Late Morning	Keynotes
Lunch	Lunch Break
Afternoon	Exhibit Hall Opens & Breakout Sessions
Evening	Welcome Reception

Day 2: Thursday, 12 August 2027*

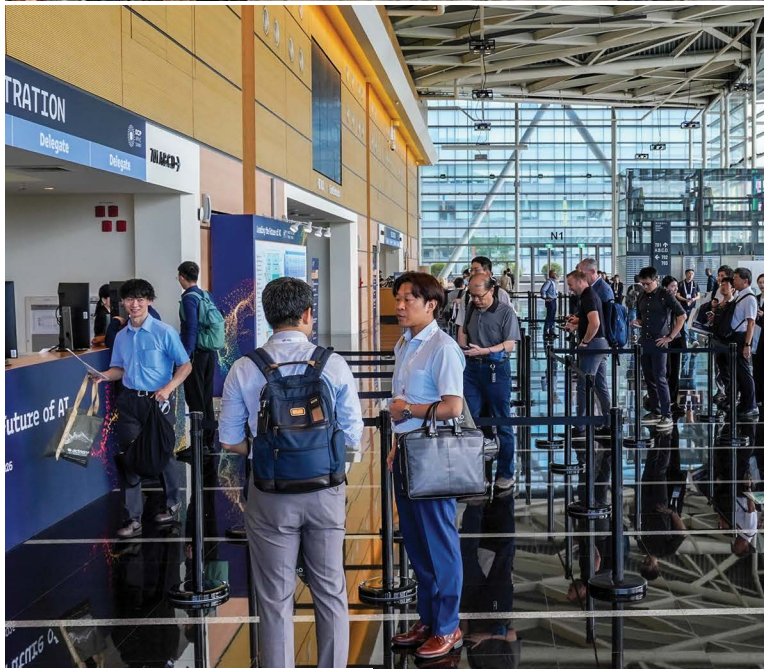
Time	Event
Morning	Breakout Sessions
Lunch	Lunch Break
Afternoon	Breakout Sessions
All Day	Exhibit Hall Open

**Schedule is subject to change.*



Taipei Nangang Exhibition Center, Hall 2 (TaiNEX 2)

No. 2, Jingmao 2nd Rd, Nangang District, Taipei City, Taiwan



Booth Sponsorship

Showcase your company's innovations at the heart of the 2027 OCP APAC Summit. Our booth sponsorship packages offer turnkey exhibits, brand visibility, and access to key decision-makers, with flexible options to match your organization's goals.

Package	Elite*	Premier*	Plus*
Price	\$50,000	\$30,000	\$15,000
Booth Size	9m x 6m	6m x 3m	3m x 3m
Complimentary Passes	15	10	7
Turnkey Booth Inclusions	• Custom Printed Back Wall (Logo or Artwork) • LED Monitor with Stand • Lead Retrieval Device • Wi-Fi Access • 120v/20A Electricity + Power Strip • Locking Counter • Choice of Carpet Color • Chairs • Waste Bin		

**OCP Tiered Membership discounts available and apply to booths only.*



Event Sponsorship

Make your brand part of the Summit experience. Event sponsorships provide prominent visibility in high-traffic areas and at networking gatherings, giving sponsors lasting exposure with attendees throughout the 2027 OCP APAC Summit.

Sponsorship Item	Price	Notes	Passes Included
Badges & Bevs (Day 0)	\$20,000	Sponsor's company logo featured on reception signage and opportunity to network with attendees and display giveaways in dedicated space.	4
Welcome Reception (Day 1)	\$20,000	Day 1 Evening: Logo on reception signage and OCP website	4
Power Up Lounge	\$15,000	Dedicated lounge area with signage and charging stations.	4
Community Lounge	\$15,000	Dedicated lounge area with signage and 1 monitor showcasing your custom content (no audio)	4
Coffee (Both Days)	\$15,000	Logo prominently featured in conjunction with coffee service	4
Lunch (Both Days)	\$15,000	Logo prominently featured on signage during lunch service	4
Water (Both Days)	\$15,000	Logo prominently featured on water stations throughout venue	4
Lanyards	\$20,000	Logo prominently featured on attendee lanyards	4
Tote Bags	\$15,000	Logo prominently featured on Summit bags	4
Tote Bags Insert (max 5)	\$3,000	Branded collateral or promotional items included in tote bags	2
Sticker Sheets	\$5,000	Logo or sponsor artwork featured on sticker sheets distributed at registration	2
Future Technologies Symposium (FTS) Sponsor	\$10,000	Logo prominently featured on signage and 5 minutes to address audience during the Symposium	4
Private Meeting Room	\$5,000	Access to a private meeting room for up to 8 people - space and furniture based on venue. (Available to Booth Sponsors Only)	N/A





2027 OCP APAC Summit – Sponsorship Contract

Event Dates: August 10–12, 2027

Venue: Tainex 2, Taipei City, Taiwan

This Agreement is made and entered into as of [date] _____ between the Open Compute Project (“OCP”) Foundation and:

Name of Organization (*how it should be displayed on OCP site*): _____

Address: _____

City: _____ State/Province/Region: _____ Zip/Postal Code: _____

Country: _____ Phone: _____

Sponsorship Logistics Contact Name: _____ Email: _____

URL you want linked to your logo: _____

This is a co-sponsorship (max 1 additional logo) Co-sponsor Name: _____

Sponsor Options for the 2027 OCP APAC Summit (the “Event”)

Booth Sponsorships

___ Elite: \$50,000 (9m x 6m booth) ___ Premier: \$30,000 (6m x 3m booth) ___ Plus: \$15,000 (3m x 3m booth)

___ Meeting Room: \$ 5,000

Event Sponsorships (Member discounts do not apply)

___ Badges & Bevs (Day 0): \$20,000	___ Coffee (Both Days): \$15,000	___ Tote Bags: \$15,000
___ Welcome Reception (Day 1): \$20,000	___ Lunch (Both Days): \$15,000	___ Tote Bag Insert (max 5): \$3,000
___ Power Up Lounge: \$15,000	___ Water Sponsor (Both Days): \$15,000	___ Sticker Sheets: \$5,000
___ Community Lounge: \$15,000	___ Lanyards: \$20,000	___ FTS Sponsor: \$10,000

** All prices listed in USD. Final invoice may reflect VAT charge in addition to sponsorship total below, if organization does not have an entity located in Taiwan. Please contact accounting@opencompute.org for clarifications.*

Tiered Membership Discount

If your company is an OCP Tiered Member, please check the applicable discount below. Must be a Member in good standing at the time of the 2027 APAC Summit. **Membership discounts apply to booths only. Marketing and Event sponsorships, speaking add-ons, and meeting rooms are not eligible for discounts.**

___ Platinum Tiered Member (15%) ___ Gold Tiered Member (10%) ___ Silver Tiered Member (7%)

Total Amount (after discounts if applicable): \$ _____

OCP Contact: Kate Hendle, Manager of Events, kate@opencompute.org

Payment Information: Acceptable forms of payment include ACH, wire transfers, credit cards and checks. If paying by check, please make checks payable to: GIS Group Global Co., Ltd., No. 382, Shin-yi Road Sec. 4, Taipei 106, Taiwan

1. *Payment must be in United States Dollars. All payments must be made to GIS Group Global Co., Ltd. and provided in cleared funds to the bank account provided on the invoice not later than net 30 days of the date of the invoice. All fees are exclusive of all applicable sales, use, value-added and similar taxes, which Sponsor shall pay in addition to the fees at the rate prevailing on the date of the invoice. Payment must be received prior to the event or the sponsorship will be considered invalid. Account must be current to participate.*
2. *Sponsor speakers are required to submit their presentation content for review by the Open Compute Foundation by the date indicated in the prospectus. Failure to submit your content for review by the foundation can result in the loss of your speaking opportunity.*
3. *Sponsor is responsible for meeting all deadlines for delivery of materials and artwork. Past due materials may be excluded from the conference program, signage, and other opportunities included in the sponsor's contribution level.*
4. *Sponsor is responsible for any shipping and receiving costs the venue may charge for materials shipped directly to the venue.*
5. *Exhibit Locations. Booth/table location assignments will be selected by the sponsor company on a first-signed, first-served basis, and may be modified by the Foundation due to changes in event layout, venue or other factors.*
6. *Restrictions in Operations of Exhibits. The OCP Foundation and its representatives reserve the right to restrict or remove exhibits which, because of noise, method of operation, materials, or for any other reason, may become objectionable to the reasonable attendee or the venue. In the event of such restriction or eviction, the OCP Foundation is not liable for any refunds, rentals, or other exhibit expenses incurred by the Sponsor.*
7. *Care of Building. The Sponsor shall not injure or deface the walls, floors, tables, or equipment of the building. The Sponsor assumes all liability for any damage incurred.*
8. *Catastrophe. In the event that because of war, fire, strike, government regulation, natural disaster, pandemic, public catastrophe, act of God, or other cause, the conference or any part thereof is prevented from being held, or is canceled by the OCP Foundation, the OCP Foundation shall determine any refund to a Sponsor after deducting any expenses incurred by the OCP Foundation but in no case shall the amount of the refund to the Sponsor exceed the amount of the fee paid.*
9. *Cancellations made by the Sponsor 6 months or more prior to the event will not be subject to any fee. Cancellations made between 3 and 6 months prior to the event are liable for 50% of the sponsorship fee or the cost of equivalent services/equipment if the sponsorship is an in-kind or barter arrangement. Cancellations made less than 3 months prior to the event are liable for the entire sponsorship fee or the cost of equivalent services/equipment. All cancellations must be made in writing to the OCP Foundation.*
10. *Trademarks. Each party retains all rights and ownership to its own trademarks and must obtain prior approval from the other party for any use of the other party's names or marks for the purpose of marketing, advertising and otherwise promoting participation in and/or sponsorship of (as described in this Agreement) the Event, which approval shall not be unreasonably withheld or delayed. Sponsor shall provide to OCP Foundation any artwork necessary for use of Sponsor's marks, name or logo. Sponsor agrees to abide by, and be bound by, the Open Compute Project Trademark Usage Guidelines, which are available at <https://bit.ly/2QwPmUN>, including as this may be updated by OCP Foundation from time to time. At the request of OCP Foundation, Sponsor will provide samples of its uses of OCP Foundation marks.*
11. *OCP Materials Release. If I am presenting at the OCP APAC Summit, I acknowledge that my Presentation and any ancillary materials I provide to OCP in connection with my Presentation, including without limitation any white paper, article, photograph, likeness, or professional biography (together, "Materials") are made available under the Creative Commons Attribution-ShareAlike 4.0 International License found at <https://creativecommons.org/licenses/by-sa/4.0/>, or any later version, and without limiting the foregoing, OCP may make the Materials available under such terms. OCP may exercise its rights hereunder in all forms and media, whether now known or hereafter developed, throughout the world in perpetuity, royalty-free. My authorization and acknowledgement above are irrevocable and extends to OCP and its agents, successors, and assigns. I hereby waive any right to inspect or approve the Recordings. I acknowledge that OCP is under no obligation to use the Recordings, or Materials if applicable, in any manner. I hereby represent that I have the authority to grant the rights and licenses herein. And if I am presenting at an OCP event, I further represent and warrant that the Materials do not and will not violate the rights of any third party, including without limitation rights in intellectual property. I also represent that, to the extent the Materials include materials owned or created by any third-party, I have obtained permission for its use consistent with the foregoing. I will provide OCP evidence of such permission upon OCP's request.*
12. *Miscellaneous. This Agreement shall be governed by the internal laws of the State of Delaware without regard to principles of conflicts of laws. Any disputes shall be heard exclusively in the state or federal courts located in Delaware, and both parties consent to the jurisdiction of such courts. Sponsor cannot assign any rights under this Agreement without the prior written consent of the OCP Foundation; any unauthorized assignment is null and void. This is the entire agreement of the parties and cannot be amended or changed except in a writing signed by both parties.*
13. *GDPR Policy. OCP will treat all information you provide in accordance with the OCP Privacy Policy posted at <http://www.opencompute.org/privacy/>. This includes cookies and any other information we may collect. By signing this contract, you acknowledge and accept OCP's Privacy Policy and give your consent to the transfer of your personal information to the United States, which may have less protection than your jurisdiction of residence.*
14. *BADGE SWAPPING: Badge swapping and/or trading is strictly prohibited at OCP events. Attendees must wear their badge at all times on the event premises. Any attendee caught without a badge will be escorted to registration to show an ID and charged a reprint fee if the badge cannot be found. If caught wearing another attendee's badge or leaving the premises with multiple badges with the intent to distribute to other attendees, all badges will be confiscated, and this person may be removed from the event. OCP keeps historical records of companies and sponsors who are regular offenders of badge swapping. OCP reserves the right to deny attendance, sponsorship, and speaking opportunities to any individuals or organizations that do not abide by OCP event regulations.*

In witness whereof, the parties have caused this Agreement to be executed by their duly authorized representatives.

Sponsor:

Signature: _____

Printed Name: _____

Title: _____

Date: _____

Open Compute Project Foundation:

Signature: _____

Printed Name: Kate Hendle

Title: Manager of Events

Date: _____

Sponsorship deadline is Monday, May 3, 2027. Sponsorships & booth locations are awarded in the order that they are received.